

# Low Noise Master Oscillator LNMO

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## OBJECTIVE AND STUDY PLAN

### Objective

The objective of this study was to design, manufacture and test an Engineering Model of a compact and low cost reference oscillator meeting the requirements specified in Updated Requirements Specifications for Reference Oscillator.

This equipment shall be free of any export licence control for use in European space programs.

### Study plan

We describe here the study plan for the tasks that have led to the development of a Low Phase Noise Reference Oscillator. The plan followed closely the SOW and divided the activity in three phases:

- Phase 1 : Review and preliminary design
  - Task 1: Requirements and Technology Review
  - Task 2: Preliminary Design
- Phase 2 : Breadboarding and design
  - Task 3: Building Block Design and breadboarding
  - Task 4: Detailed Design
- Phase 3 : Manufacture, Assembly, Test and Conclusions
  - Task 5: Manufacture and Assembly
  - Task 6: Test
  - Task 7: Overall Assessment and Recommendations

**Phase 1** dedicated to the review of the requirements and current technology as well as the identification of criticalities which has resulted in the definition of a preliminary design. This Phase has been concluded by a Preliminary Design Review.

**Phase 2** dedicated to the detailed design of the oscillator, including the development and validation (at breadboard level) of the identified critical building blocks. This Phase has been concluded by a Detail Design Review.

**Phase 3** dedicated to the manufacture, assembly, test of 6 Low Noise Reference Oscillators, as well as the definition of plans and recommendations for qualification. This Phase has been concluded by the Final Review.

## PHASE 1

### Task1: Requirements and Technology Review

Competitor state of the art

After some space OCXO manufacturer data sheets analysis (TEMEX, RAKON (publication), SYMETRICOM, WENZEL, FEI (publication), ASTRIUM), none warranty at 100% ESA requirements.

Customers needs

All identified customer needs at 10MHz are covered by the Low Noise Reference Oscillator but only a few demands request this level of specification, target price is depending on OCXO performances and quantity.

Reference Oscillator Technology Assessment

The low noise reference oscillator will be a crystal oscillator built with in mixed technologies (PCB+SMD parts+ encapsulated macro functions) using a simple oven regulation and an oven size reduce to its minimum in order to gain in term of size, weight , consumption and cost.

Risk and cost assessment

Design	Risk	Actual cost	Possible gain	cost 60units/year
New design	-phase noise at 10Hz - frequency stability vs temperature range	0.72	change crystal source and with use of commercial parts	0.67 0.28

Cost normalized to current Spectratime OCXO design

### Task 2: Preliminary Design

#### Breadboard Preliminary Design

##### Metrologic electronic solutions

In order to reach the contract specification several schemes have been tested on a preliminary breadboard. Design was essentially based on tests performed on two types of oscillators and three types of buffers. All the schemes have been preselected thanks to the large experience of Spectratime experts. The priority was to reach the phase noise specification, by selecting schemes and crystals.

- Oscillator
  - Colpitts oscillator buffered by a common emitter stage
  - Cascode Colpitts oscillator buffered by a common base stage
  - Colpitts oscillator with frequency output performed at crystal level buffered by a common base stage
  - SPECTRATIME current solution: cascode Butler oscillator with ACG
  - Simplified SPECTRATIME solution: Butler oscillator with ACG
  - Cascode Butler oscillator with frequency output performed at crystal level buffered by a common base stage without ACG
- Buffer
  - Common base output power amplifier
  - Cascode output power amplifier
  - Push-pull output power amplifier
- Voltage regulation: the current Spectratime voltage regulation has been used with an improvement of its filtering.
- Oven loop: a single oven with a proportional loop.

##### EEE parts pre-selection

- Signal transistors:2N2222A,2N2907A,2N2369A,2N4416,2N2857,BFR92
- Power transistors:BDS20 or equivalent
- Varactor : DH76150 and DH71330
- Schottky diode:1N5819UR-1
- SC cut Crystals: 5MHz and 10MHz in HC40 or HC37 holder from: Bliley, NEL and KVG

# LNMO Preliminary Design

## Global block diagram

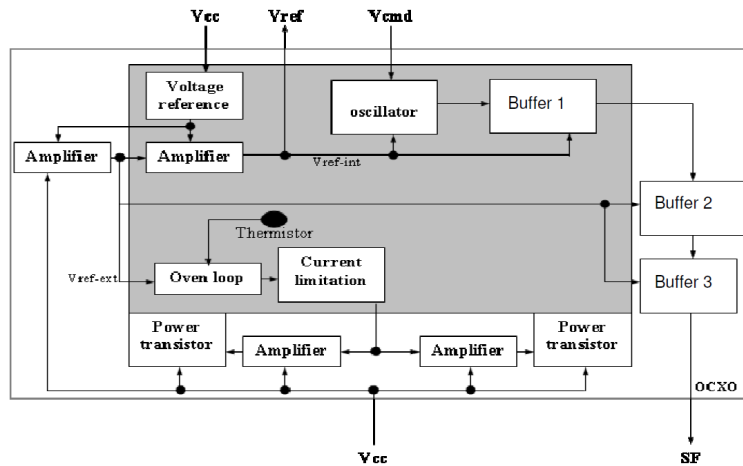


Fig. 2

In the gray area of the block diagram are all the thermal sensitive functions which will be implanted on the heated board. A thermal simulation of this board has to be performed taking into account all components sensitivities in order to place each of it in a compatible area.

## Thermo mechanical structure

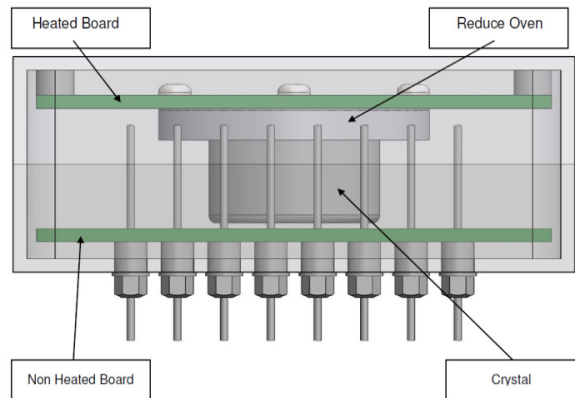


Fig. 3 Package size target: 50x50x30 mm

A thermo-mechanical analysis has been performed in order to identify all the structure resonance and thermal behavior:

- first resonance was found at 825Hz and has been increased up to 1250Hz by increase of the PCB thickness (1.6mm to 2.4mm)

Nom du modèle: Solution 2  
 Nom de l'étude: Modal  
 Type de tracé: Fréquence Déplacements1  
 Mode: 1 / Valeur = 828.4 Hz  
 Echelle de déformation: 0.000704981

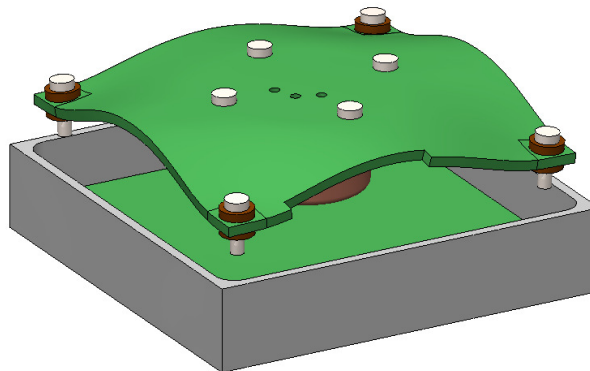


Fig.4 Mode shape, 1st frequency (828.4 Hz), PCB bending, Z direction

- a large area at heated board level has been identified with a thermal gradient compatible with required frequency stability (<math>0.4^{\circ}\text{C}</math> at PCB level and <math>0.05^{\circ}\text{C}</math> at crystal level) .

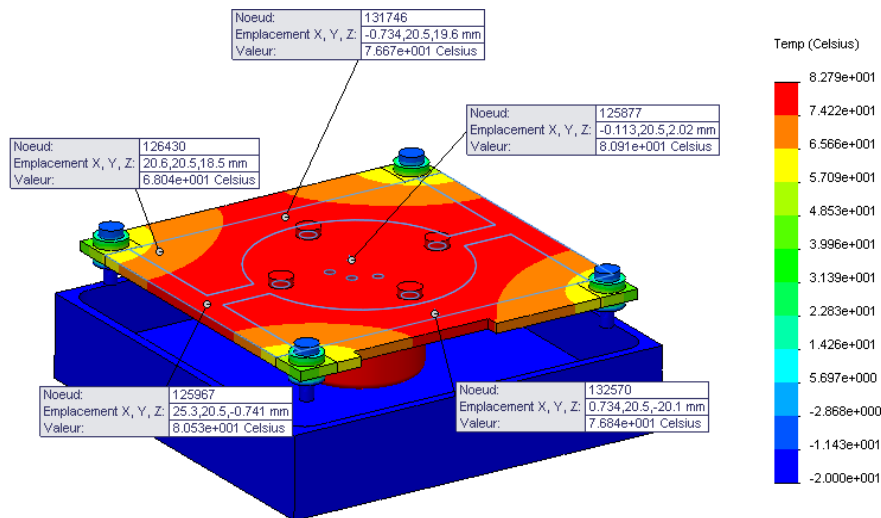


Fig. 5 Temperature plot, cold case, upper PCB ( $^{\circ}\text{C}$ )

### Critical Building Blocks Identification

Four blocks are critical:

- Oven, found a compromise between size (consumption) and temperature regulation (frequency stability, phase noise at  $f \leq 1\text{Hz}$ )
- Output amplifier (level and phase noise)
- Oscillator and Crystal (aging, phase noise and frequency stability)
- Filtering (phase noise, spurious).

### Updated Requirements

Some parameters have been updated or added:

- Update: output power, spurious, phase noise, supply voltage, power consumption, warm up duration, random vibration and shock levels,
- Added: sine vibration, warm up power, start up time, retrace, magnetic field sensitivity

### Preliminary test plan

Tests will be performed on 6 EM:

- initial tests on 6 units
- vibration and shocks on 2 units
- radiation tests on 4 units
- final tests on 6 units

## PHASE 2: BREADBOARDING AND DESIGN

### Task 3: Breadboard design

This preliminary design has been performed in order to test all the preselected solutions and has been mounted in a standard rubidium commercial package. All functions have been implemented on a dedicated PCB with several possibilities of configuration.

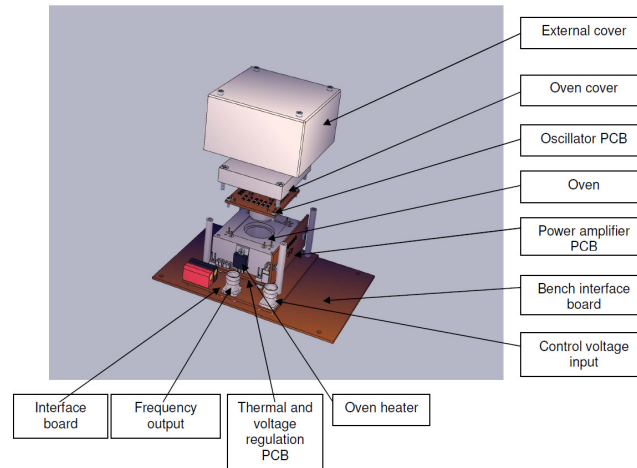


Fig. 1 breadboard design

## Breadboards Tests Results

Only some measurements are representative to the final design: phase noise, output level, harmonics, and frequency stability versus load

The others parameters are linked to the thermo- mechanical design and will be measured on the EM.

Oscillator choice

During initial tests two configurations have given results close to the target:

- Colpitts with output at crystal level , buffered by a common base stage
- Butler single transistor with ACG , buffered by a common collector stage
- As cost reduction is one of the objectives of this study we preferred work on the optimization of the Colpitts solution which uses less actives parts.

Optimization of Colpitts oscillator with frequency output performed at crystal level

Except phase noise all measurable parameters have been reached during bread boarding phase.

All 10MHz crystals have given similar phase noise performances. Final choice will be done after tests on EM.

5 MHz crystals are too sensitive to drive level and after multiplication by 2, the 10MHz phase noise specification can't be reached.

Phase noise has to be improved on EM:

- From 1Hz to 10Hz, it is linked to crystal loaded quality factor
- From 10Hz to 1kHz , it is linked to amplifier transistor flicker noise

### Task 4: Detailed Design

#### Electrical Design

##### Crystal definition

In order to reach all the LNRO specified performances we have to use an SC cut overtone 3 swept crystal resonator. Two specifications have been issued: 10 MHz SCP3 resonator in HC37U and HC40 holder

As we have obtained the same results with all types, we will finalize our choice after EM testing. However, our preference is the crystal in the HC37U holder.

## Oscillator and power amplifier

After having tested several schemes on the preliminary breadboards we have chosen to use:

- Colpitts oscillator with frequency output performed at crystal level buffered by a common base stage:A2P-Y034A
- Common base output power amplifier:A2P-Y012A

This configuration gives us the best phase noise results.

## Voltage regulation

For voltage regulation we have chosen a 1N819A zener filtered by a low pass filter and buffered by an operational amplifier and a 2N2222A transistor. With 15V supply voltage the regulated voltage will be 10V and with 12V supply voltage the regulated voltage will be 8V. The voltage regulation will be completed with low pass RC filter at each stage level.

## Oven loop regulation

For the oven loop we have chosen to use a proportional integer regulation in order to can generate a larger gain in the loop without oscillation and minimize the loop error. With a proportional regulation the gain is limited to 100, otherwise the loop oscillate.

## Components selection

During bread boarding test some actives components have been tested and selected:

- At oscillator level we can use different transistors: BFR92 or 2N2369A
- At first common base buffer level we can use different transistors:BFR92 or 2N2369A
- At common base power buffer level ( 2 stages) we can use different transistors:BFR92, 2N2369A or 2N2222A
- For voltage regulation buffer we will use a 2N2222A
- For heating power transistor we will use 2 BDS20 in TO257 package
- For oven loop current limitation we will use a 2N2222A
- For the oven loop regulation and the voltage regulation we will use an LM124 or a RH1014 operational amplifier
- For voltage reference we will use a 1N829A
- For supply polarity inversion protection ,we will use a diode 1N5819UR-1
- All these components, except the BDS20, will be in SMD technology
- For passives components we will use capacitors, resistors and inductors in SMD technology.

Colpitts oscillator + common base stage + 2 common base stages +voltage and thermal regulation

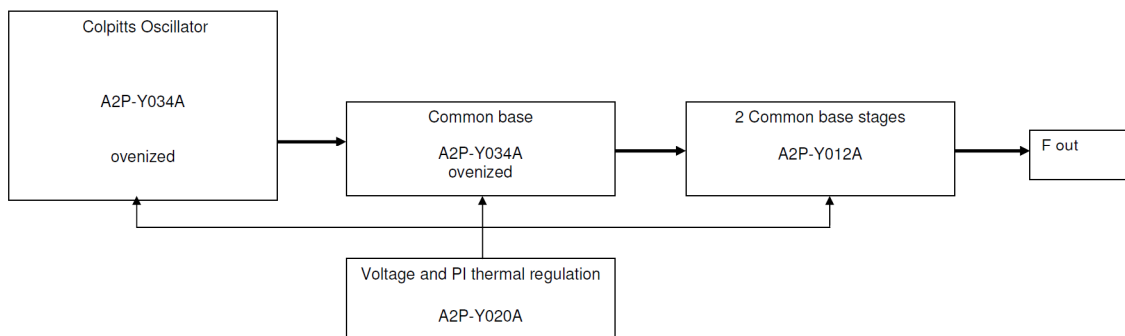


Fig. 6 Electrical block diagram

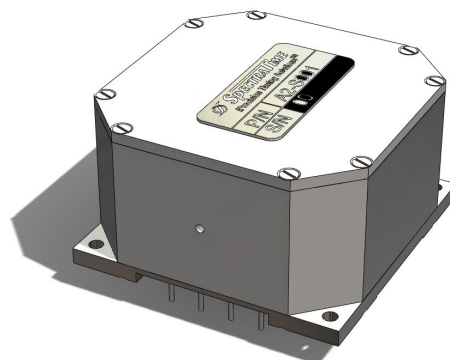


Fig. 7: Mechanical design (50x50x30 mm)

### PHASE 3

#### Task 5: Manufacture and Assembly

6 EM have been manufactured according to MATV document, LNROA2X:

- 4 dedicated to radiation tests
- 2 dedicated to environmental tests

#### Task 6: Tests

HC37U LNRO design has demonstrated its ability to reach the targeted specification, only HC40 LNRO behaviour versus temperature has to be improved.

All units have successfully passed the qualification tests, no degradation between initial and final tests.

#### Radiation test

This test has been performed at ESTEC. The OCXO has been irradiated with a cobalt 60 source in the following conditions:

- Measurement with TIMEPOD 5330A: RF output level, phase noise and short term stability
- 4 OCXO with a dose rate of 36rad/hour up to 10krad cumulated dose
- Measurement with TIMEPOD 5330A: RF output level, phase noise and short term stability
- 4 OCXO with a dose rate of 360 rad/hour up to 100krad cumulated dose
- Measurement with TIMEPOD 5330A: RF output level, phase noise and short term stability
- The dose rate is adjusted by the distance from the considered OCXO to the CO-60 beam

### SpectraTime Irradiation Tests at ESTEC Co-60 Facility

Time required to reach each step when performing a non-continuous measurement of short term stability

The radiation emission affects a specific parameter to be measured, in this case called short term stability, Therefore it is required to stop the radiation source emission and take the measurement of short term stability, It will require no more than few seconds to perform the short term stability

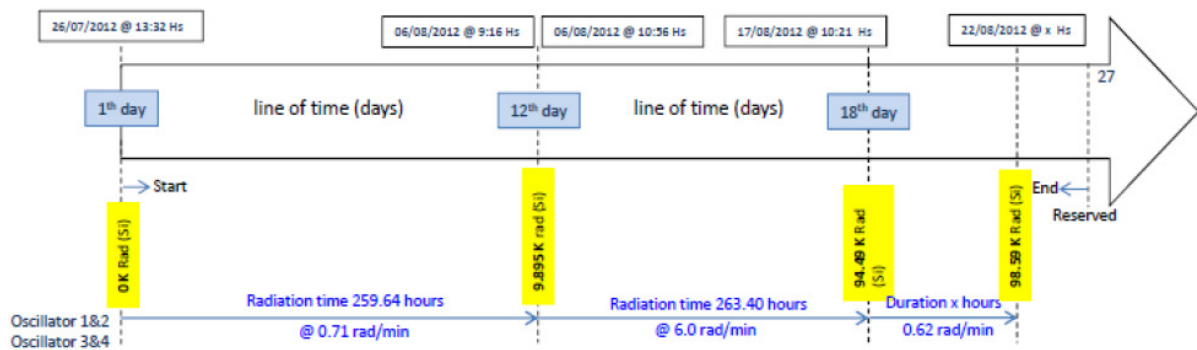


Fig.8

SN02

TEST RESULTS	Specification	initial	Final	Comments
LNRO Serial Number		SN02	SN02	
Crystal type		HC37	HC37	
		KVG	KVG	
Active parts type		indus	indus	
Output signal under 50Ω				
Output signal level(dBm)	10+/-1	10.2	10.2	
Harmonics/sub-harmonics(dBc)	-40	-50	-52	
Spurious(dBc) 0.1MHz to 1MHz	<-120	<-120	<-120	
1MHz to 1GHz	<-100	<-108	<-108	
Return loss(dB in-band +/-50kHz )	15	30	30	
Frequency accuracy	1E-8	<1E-8	<1E-8	
Frequency adjustment	+/- 2E-7	3.25E-7 1.15E-7	4.65E-7 2.53E-7	Drift linked to radiation Non swept crystal
Frequency stability over life(1)	+/-2E-7	1.71E-7	1.71E-7	
versus operating temperature range under vacuum	+/-1E-9	2E-10	4E-10	Difference linked to aging during initial test
aging	+/-1.2E-7			
sensitivity to Power supply 15V +/- 5% per V		1E-11	1E-11	
Sensitivity to load (50 ohms +/-10%)		6E-11	6E-11	
short term stability(1s)	1E-12	7E-13	7E-13	
sensitivity to magnetic field per Gauss +/- 2 Gauss	2E-11	1E-10 Y	1E-10 Y	Compliant in the other directions
SSB phase noise (dBc/Hz)	-110 -135 -150 -160 -160 -160	-110 -140 -154 -164 -169 -170	-112 -143 -155 -164 -167 -169	Improvement linked to crystal stabilization
Power consumption(W)	-20°C +60°C	2.5W 1W	1.4 0.6	1.43 0.7
Power consumption during warm-up at -20°C		4W	4.64	4.65
Warm-up time at -20°C		30min	7	7
Retrace		+/- 5E-9	1.2E-9	1E-9
Start up time at -20°C		10s	<1s	<1s
Dimensions(cm3)		75	75	75
Mass(g)		100	98	98

Note 1: as aging isn't measured on EM we will take worst case condition for calculation, +/-1.2E-7 for aging and +/-5E-8 for radiation.

SN02

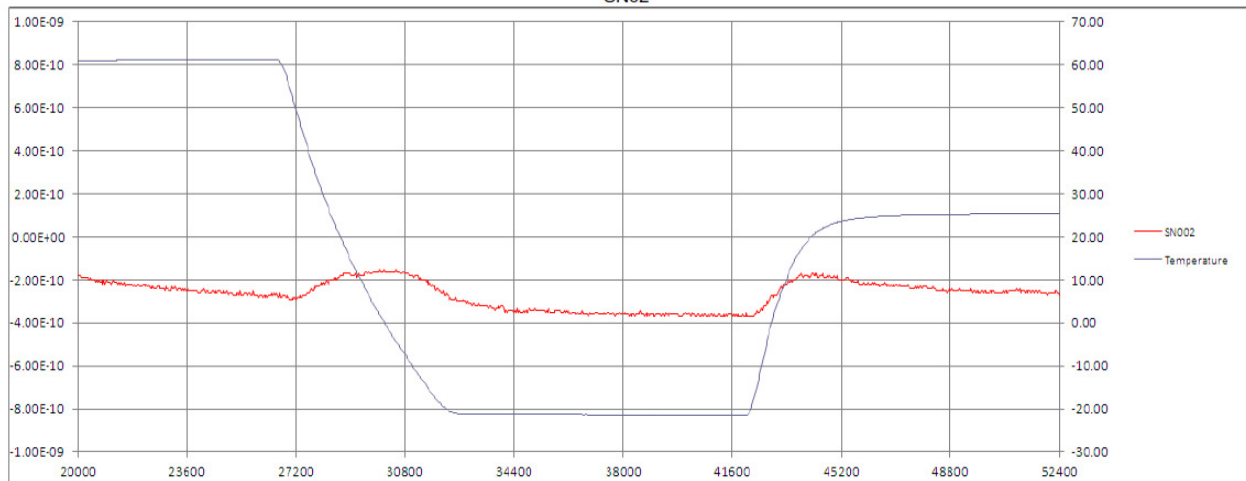




Fig 9: Stability versus temperature

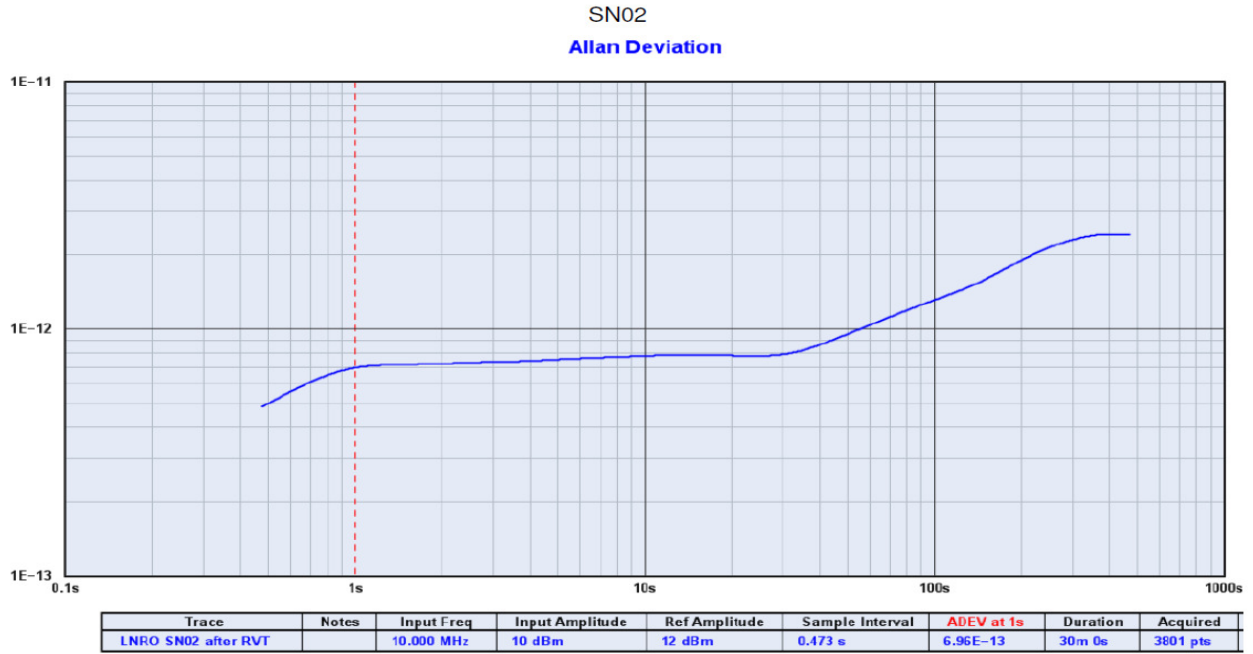


Fig. 10 Short term stability

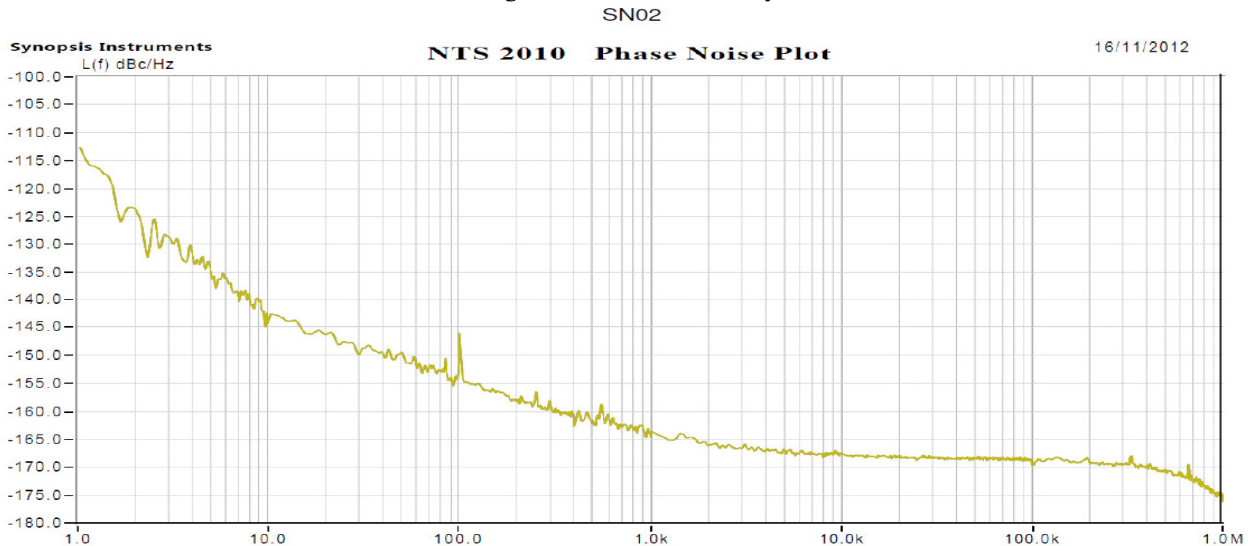


Fig. 11: Phase noise

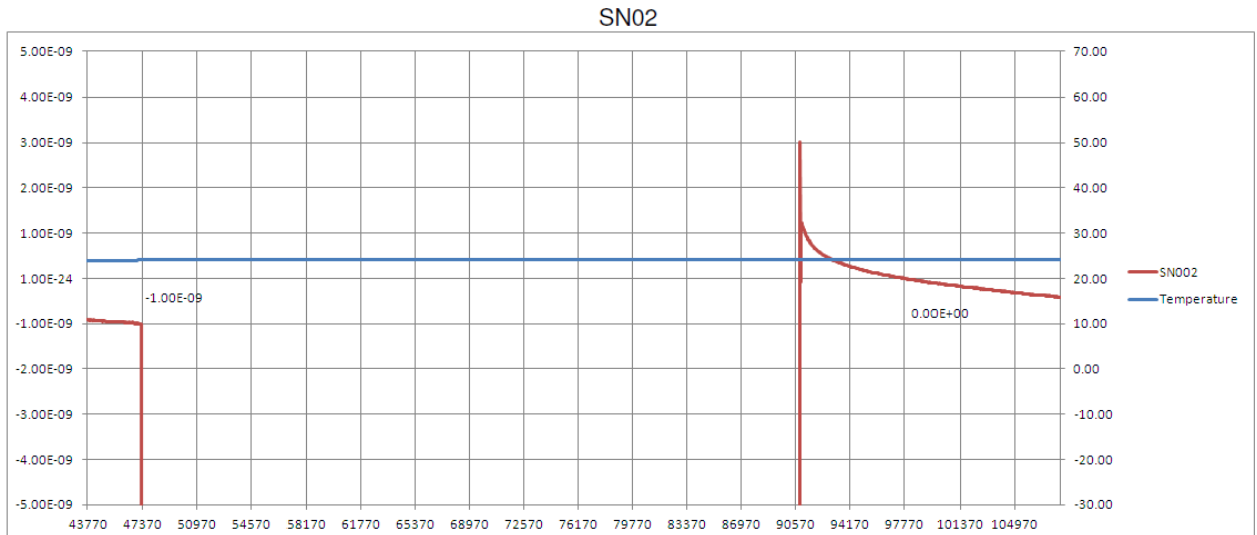


Fig 12: Retrace

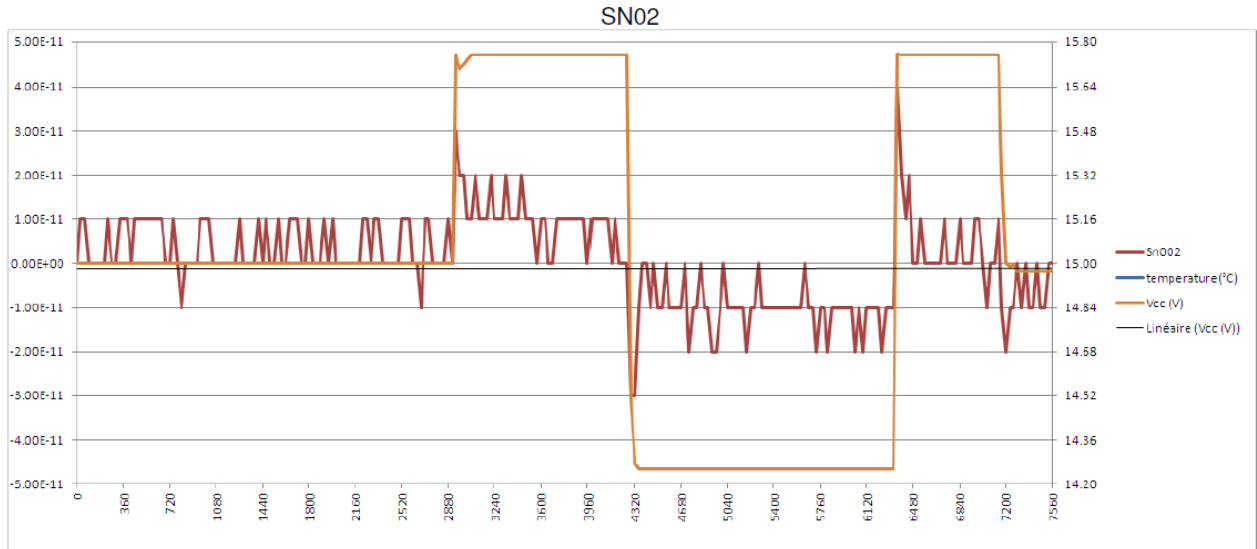


Fig 13 Frequency stability versus supply voltage variation 15V +/- 5%

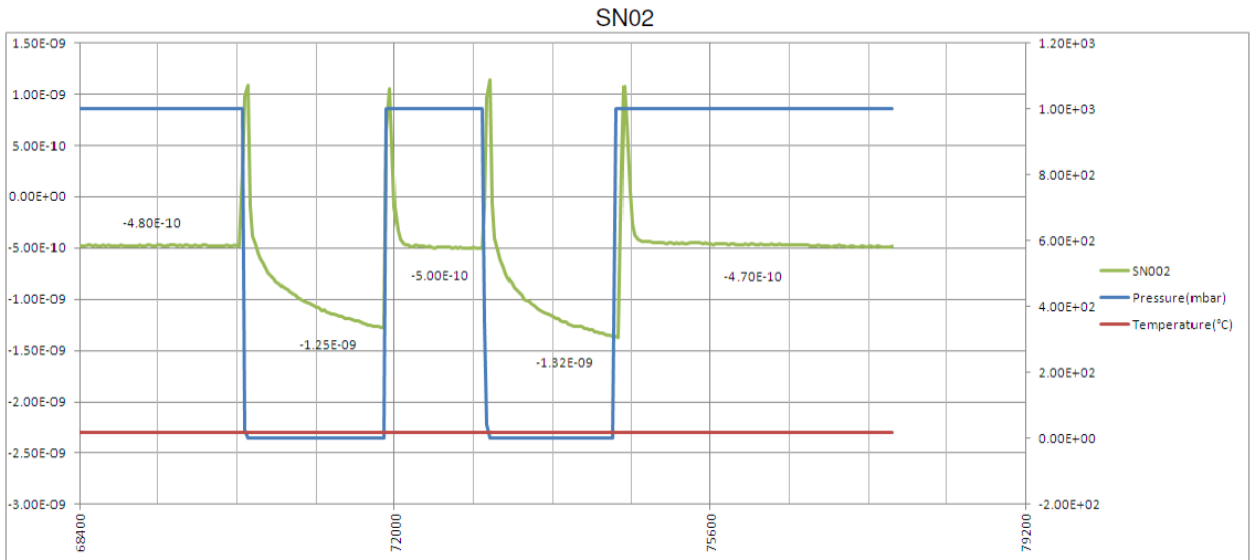


Fig 14: Frequency sensitivity to pressure

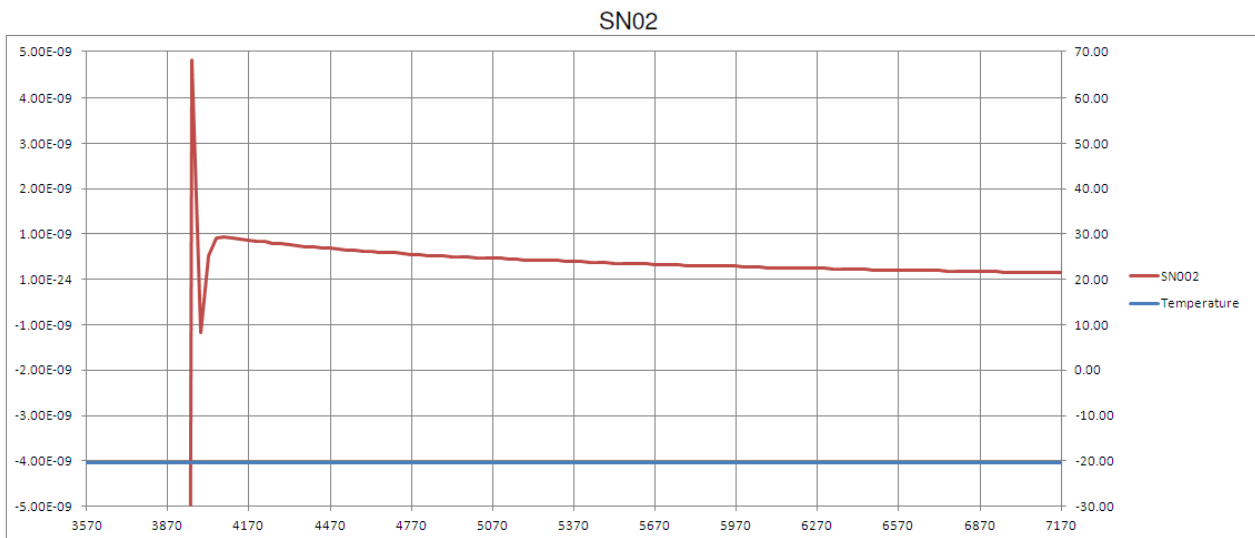


Fig15: warm-up at -20°C

**Environmental tests**

**Test during vibration tests at Galileo FOC qualification level**

		To	After sine Z	After sine X	After sine Y	After random 1 Y	After random 1 X	After random 1 Z
SN06	Frequency(Hz)	98.65	98.650	98.625	98.62	98.611	98.608	98.634
	Vref (V)	10.0674	10.065	10.067	10.067	10.067	10.068	10.0677
	Level (dBm)	11	11	11	11	11	11	11
	Harmonic (dBC)	-40	-40	-40	-40	-40	-40	-40
	Consumption (mA)	277 117.7	276 118	277 116	277 118	277 117	277 115	277 118
SN07	Frequency(Hz)	99.394	99.403	99.397	99.397	99.428	99.435	99.392
	Vref (V)	10.0736	10.073	10.073	10.073	10.076	10.076	10.0746
	Level (dBm)	10.4	10.4	10.4	10.4	10.6	10.6	10.6
	Harmonic (dBC)	-46	-46	-46	-46	-45	-45	-46
	Consumption (mA)	277 127.9	276 129	276 130	277 129	277 127	277 124	277 125

**Test during random 2 vibration**

		To	After random 2 X,Y,Z
SN06	Frequency(Hz)	98.665	98.665
	Vref (V)	10.071	10.070
	Level (dBm)	10.7	10.7
	Harmonic (dBC)	-40	-40
	Consumption (mA)	277 118	280 117
SN07	Frequency(Hz)	99.437	99.416
	Vref (V)	10.075	10.075
	Level (dBm)	10	10.1
	Harmonic (dBC)	-47	-47
	Consumption (mA)	277 125	280 127

**Tests during Mechanical shocks**

		To	After X	After X,Y	After Z
SN06	Frequency(Hz)	98.726		98.635	98.6
	Vref (V)	10.067		10.067	10.067
	Level (dBm)	11		11	11
	Harmonic (dBC)	-40		-40	-40
	Consumption (mA)	280 115		270 115	270 115
SN07	Frequency(Hz)	99.45	99.48	99.52	99.612
	Vref (V)	10.078	10.078	10.078	10.075
	Level (dBm)	10.2	10.2	10.2	10.2
	Harmonic (dBC)	-48	-48	-47	-47
	Consumption (mA)	280 125	280 125	280 125	280 125

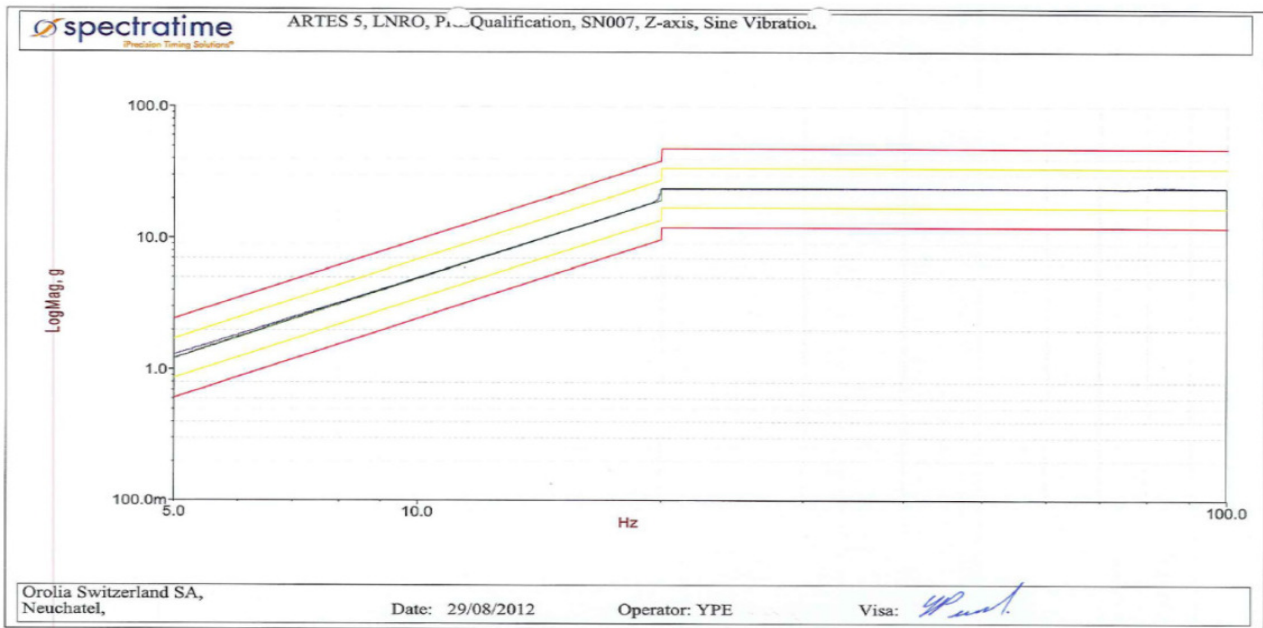


Fig. 16 Sine level applied on the 3 axis: 25g

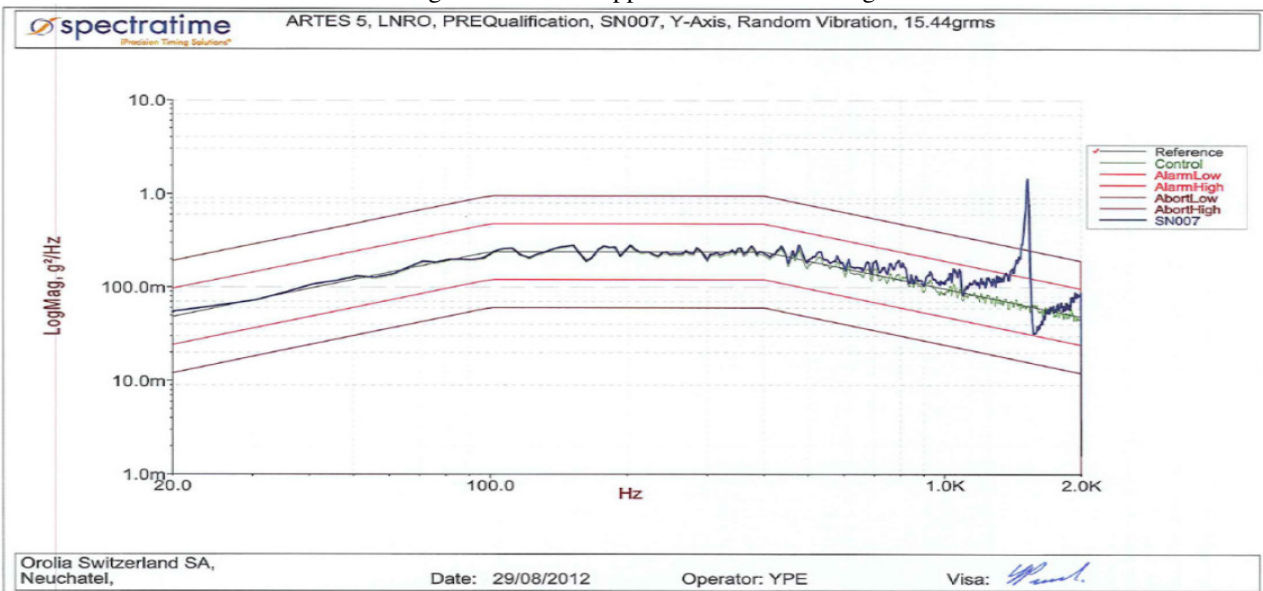


Fig. 17 FOC Random vibration level applied on X and Y axis

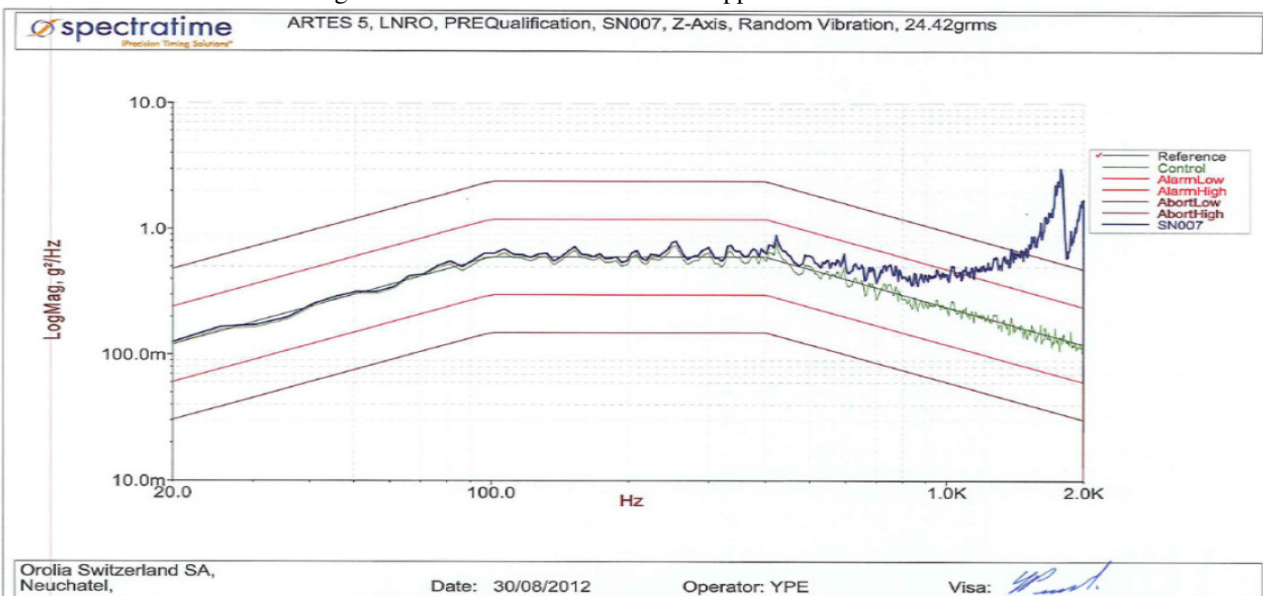


Fig. 18 FOC Random vibration level applied on Z axis

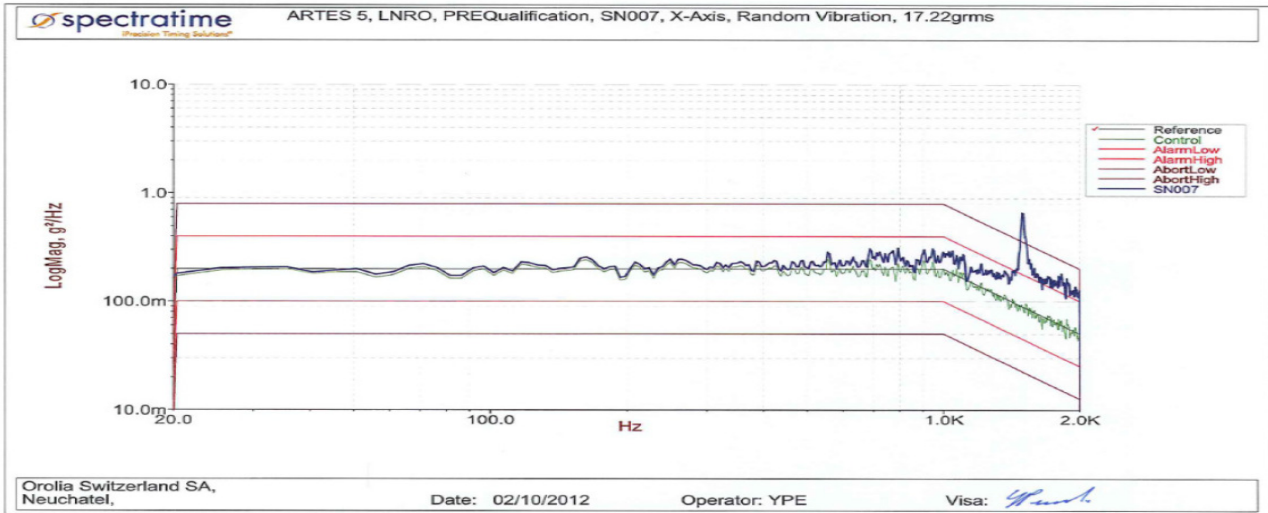


Fig. 19 Random 2 vibration level applied on X and Y axis

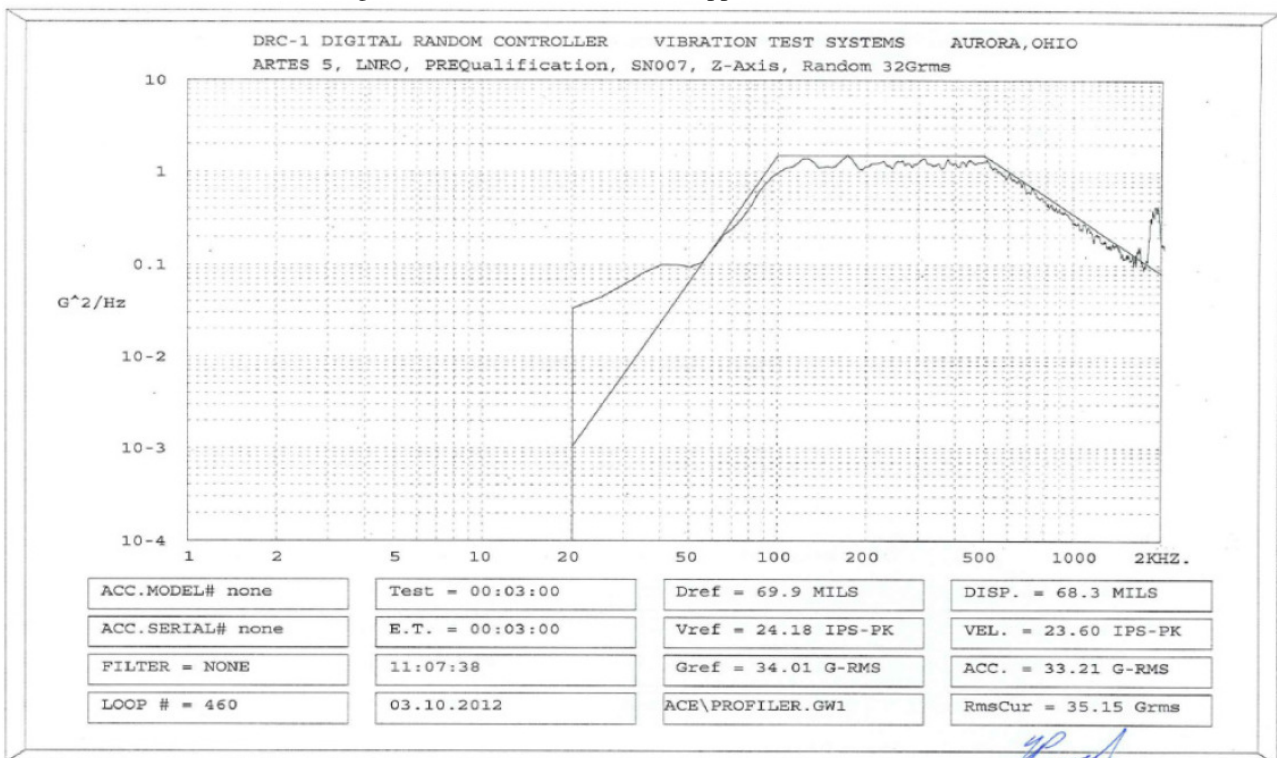


Fig. 20 Random 2 vibration level applied on Z axis



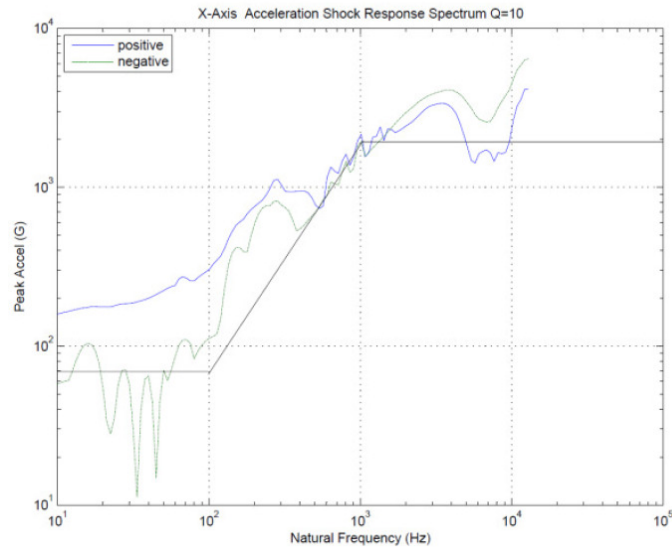


Fig.21 shock in X axis

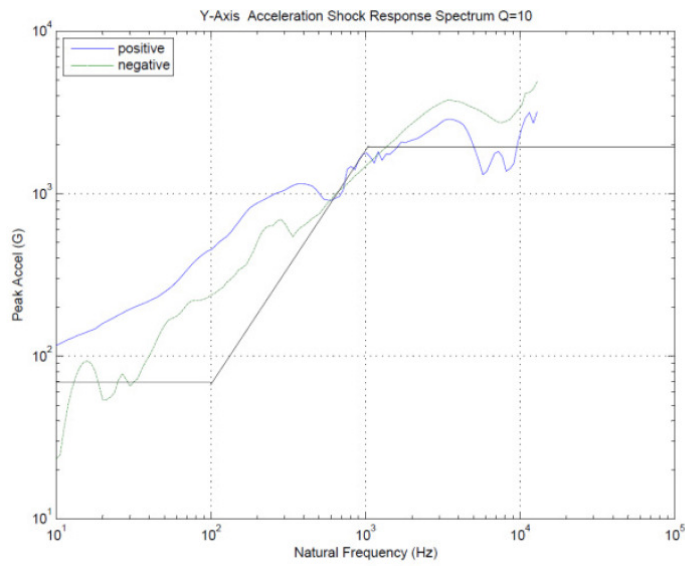


Fig. 22 Shock in Y axis

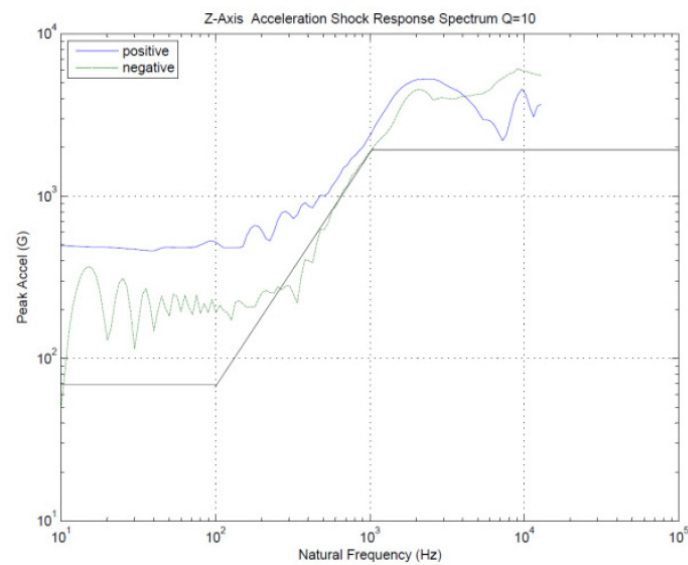


Fig. 23 Shock in Z axis

## SN07

TEST RESULTS	Specification	Initial	Final	Comments
LNRO Serial Number		SN07	SN07	
Crystal type		HC37 KVG	HC37 KVG	
Active parts type		indus	indus	
Output signal under 50Ω				
Output signal level(dBm)	10+/-1	10.7	10.4	
Harmonics/sub-harmonics(dBc)	-40	-45	-48	
Spurious(dBc) 0.1MHz to 1MHz	<-120	<-120	<-120	
1MHz to 1GHz	<-100	<-108	<-108	
Return loss(dB in-band +/-50kHz )	15	23	23	
Frequency accuracy	1E-8	<1e-8	<1e-8	
Frequency adjustment	+/- 2E-7	+1.9E-7 -0.91E-7	+2.53E-7 -0.31E-7	
Frequency stability over life(1)	+/-2E-7	1.71E-7	1.71E-7	
versus operating temperature range under vacuum	+/-1E-9	1E-9	1.08E-9	
aging	+/-1.2E-7			
sensitivity to Power supply15V+/- 5% per V		2.5E-11	4E-11	
Sensitivity to load (50 ohms +/-10%)		3E-11	3E-11	
short term stability(1s)	1E-12	6.7E-13	7.2E-13	
sensitivity to magnetic field per Gauss +/- 2 Gauss	2E-11	<b>5E-11</b> <b>Y</b>	<b>5E-11</b> <b>Y</b>	Compliant in the other directions
SSB phase noise (dBc/Hz)	-110 -135 -150 -160 -160 -160	-112 -141 -154 -164 -168 -169	-112 -140 -154 -164 -168 -169	
Power consumption(W)	-20°C +60°C	2.5W 1W	1.475 0.715	1.435 0.68
Power consumption during warm-up at -20°C		4W	<b>4.63</b>	<b>4.65</b>
Warm-up time at -20°C		30min	7	7
Retrace		+/- 5E-9	5.9E-10	3.5E-10
Start up time at -20°C		10s	<1s	<1s
Mechanical resonance (Hz)				
	X axis		881	876
	Y axis		860	863
	Z axis		1942	1832
Dimensions(cm3)		75	75	75
Mass(g)		100	98	98

Note 1: as aging isn't measured on EM we will take worst case condition for calculation, +/-1.2E-7 for aging and +/-5E-8 for radiation.

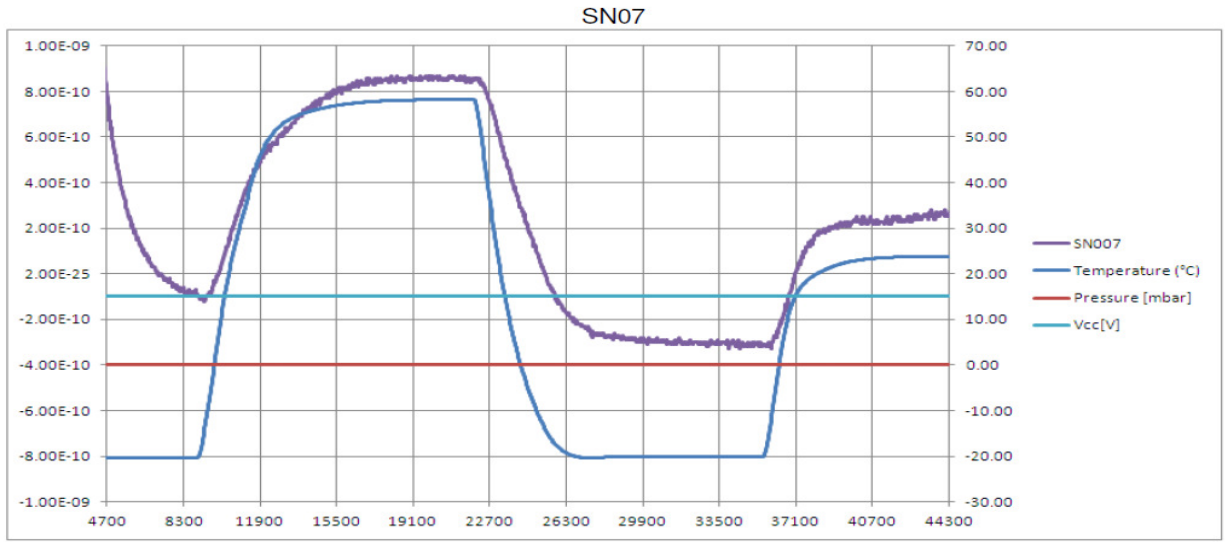


Fig. 24 Frequency stability versus temperature

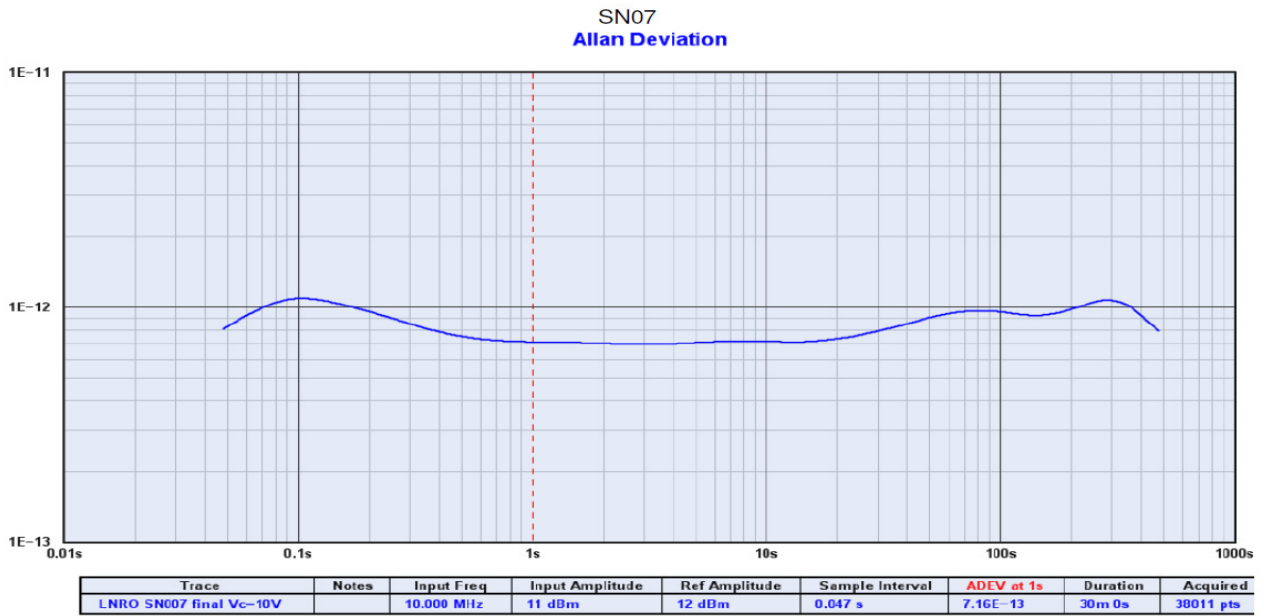


Fig. 25 Short term stability

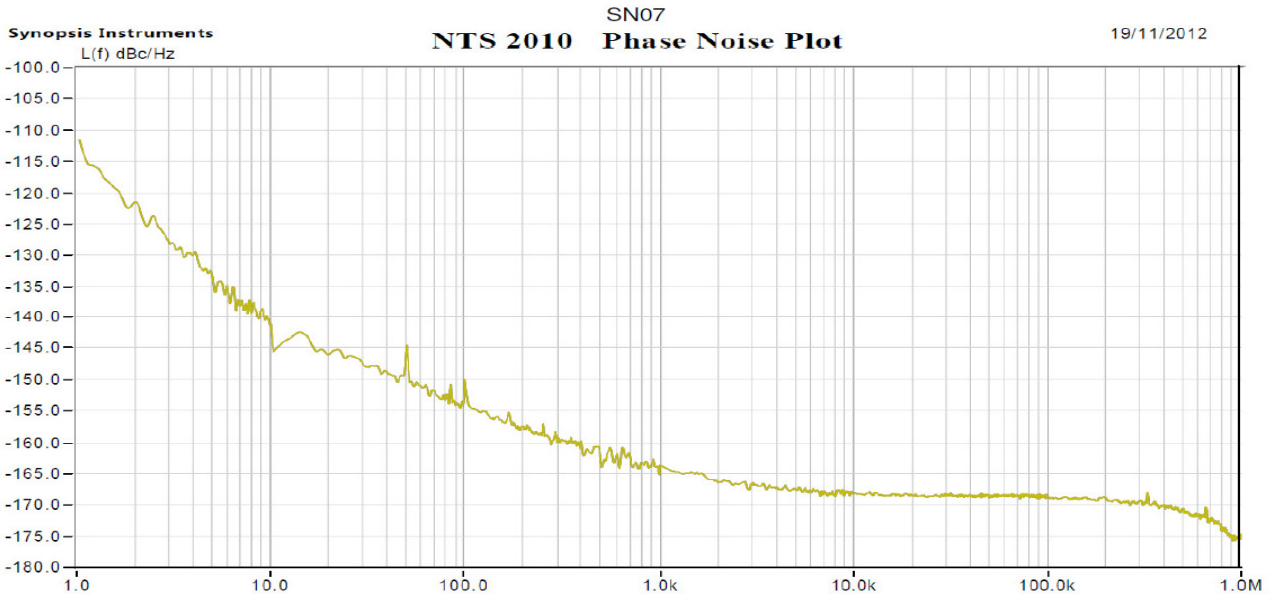


Fig. 26 Phase noise



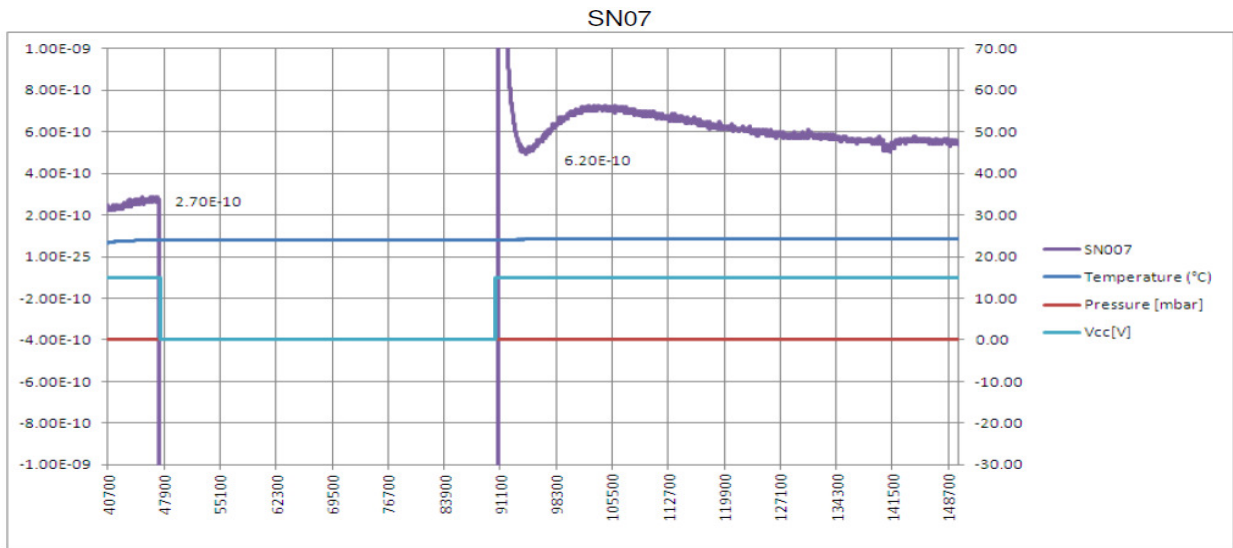


Fig. 27 Retrace

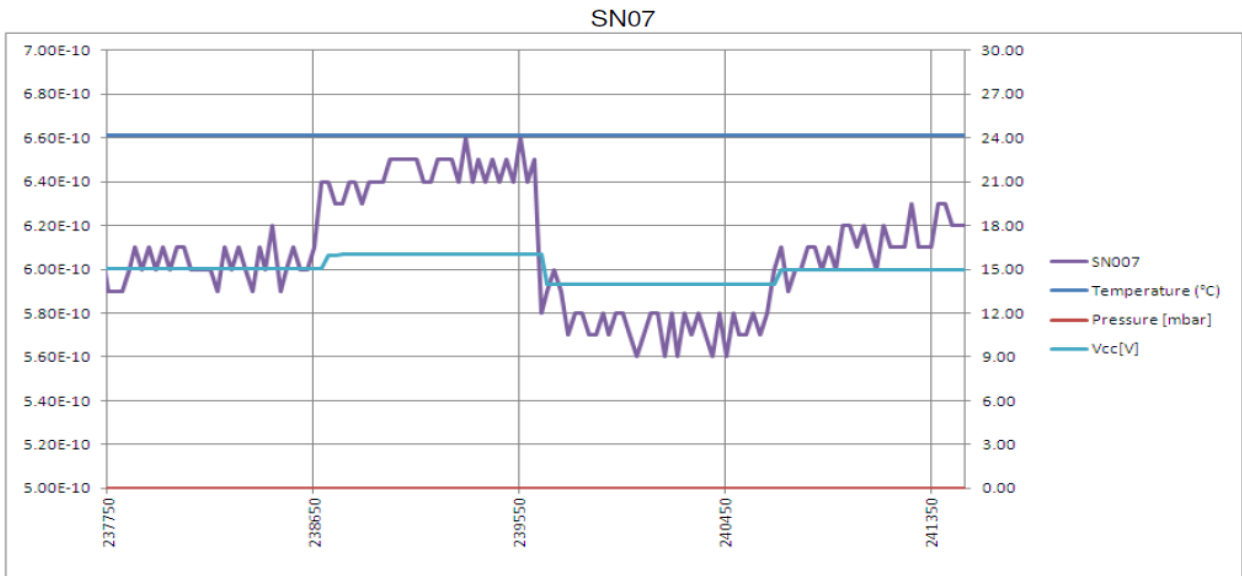


Fig. 28 Frequency stability versus Supply voltage variation 15V $\pm$  5%

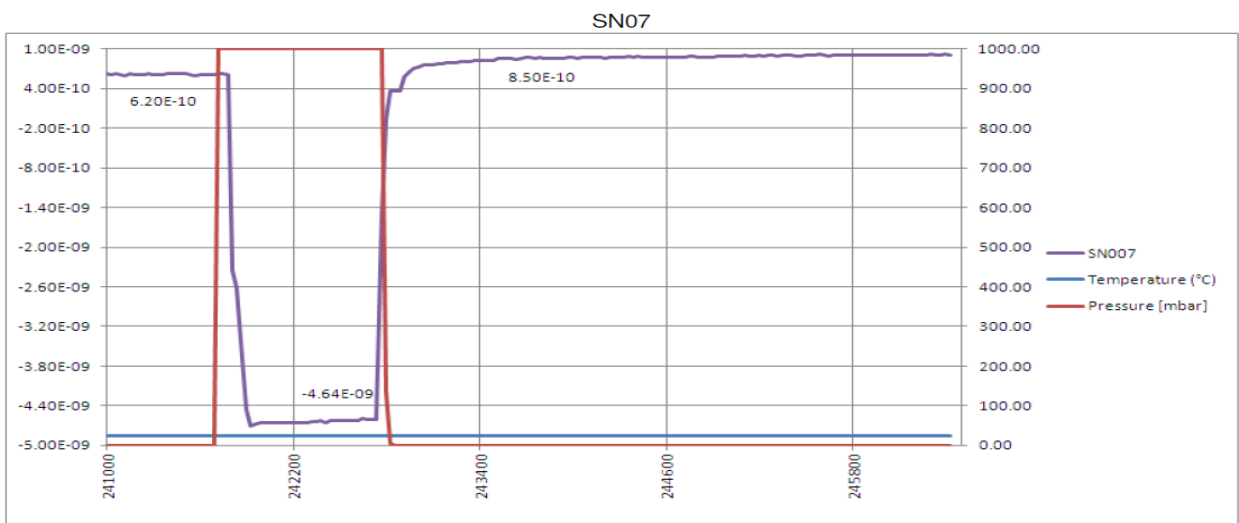


Fig. 29 Frequency sensibility to pressure

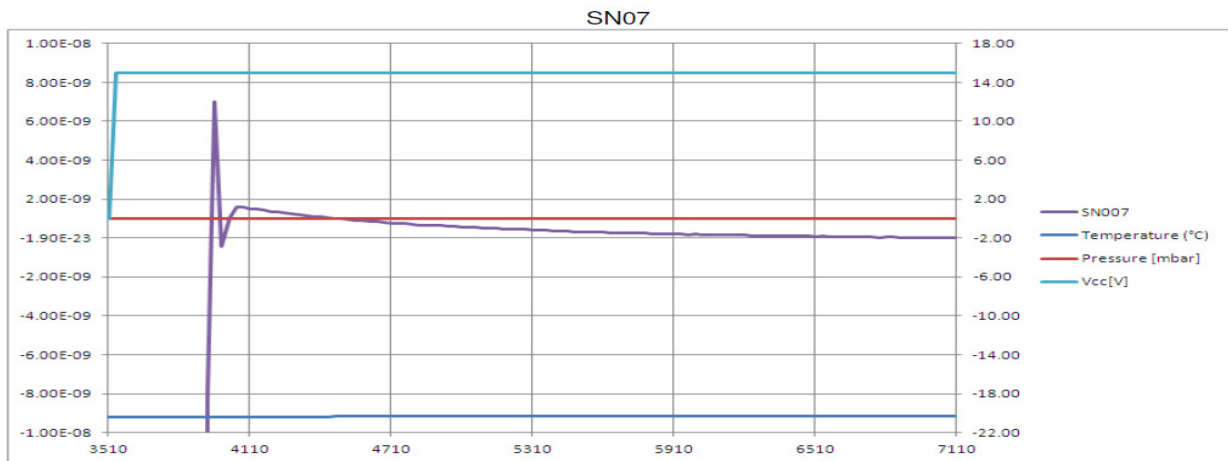


Fig. 30 Warm-up at -20°C

### Task 7: Overall Assessment and Recommendations

LNRO HC37 design has given 100% compliance versus targeted specification, SpT preferred solution.

Warm up power consumption isn't a real non compliance. Since we have a wide margin on warm up duration, heating power can be reduced.

LNRO HC40 design has to be modified in order to improve its stability versus temperature range. The oven will be redesigned like the HC37 design.

All units have successfully passed the qualification tests, no degradation between initial and final tests.

Some modifications have to be applied on the LNMO design in order to improve its assembly and tuning parts accessibility:

- The oven for HC40 crystal has to be modified in order to improve the frequency stability versus temperature range. As for the HC37U crystal the oven has to be closed..
- Minor PCB modifications in order to improve:
  - tuning parts accessibility , increase pads size
  - heating power transistor wiring , increase pads hole diameter
  - output connection wiring, move pads connections of 1mm
- all these modifications will improve the LNMO manufacturability without compromising the performances achieved on EMs

LNMO Cost and Competition Status Assessment

LNMO design covers all identified demands in term of performances and cost.

Conditions:

- Parts procurement for a minimum of 50 units
- Units manufacturing by minimum quantity of 20

### CONCLUSION

#### Design

LNRO HC37 design has given 100% compliance versus targeted specification, SpT preferred solution (Warm up power consumption isn't a real non compliance. Since we have a wide margin on warm up duration, heating power can be reduced).

LNRO HC40 design has to be modified in order to improve its stability versus temperature range. The oven will be redesigned like the HC37 design.

#### Preliminary qualification tests

All EM have successfully passed the preliminary qualification tests, no degradation between initial and final tests.

#### Cost and Competition

LNRO design covers all identified demands in term of performances and cost with below conditions:

- Parts procurement for a minimum of 50 units
- Units manufacturing by minimum quantity of 20

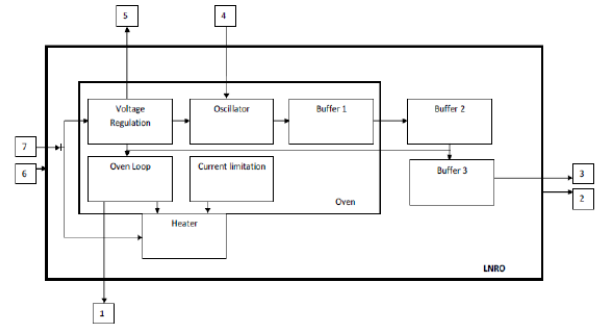
2 projects have been won against European competitors and a preliminary specification has been issued, see next pages.



**SPECIFICATIONS**

Type A2x-S001 at 10MHz				
Parameter	Value			
Dimensions	50x50x30 mm			
Output signal frequency	10 MHz*			
Frequency long term stability, 1st year	$< \pm 3 \times 10^{-8}$ / year			
Average ageing per day after 1 month	$< \pm 1 \times 10^{-10}$ / day			
Frequency long term stability, years after	$< \pm 1 \times 10^{-8}$ / year			
Frequency short term stability	$< 1 \times 10^{-12}$ (0.1-10 s)			
Frequency stability over full temp. range	$< \pm 1 \times 10^{-9}$			
Frequency adjustment	$> \pm 2.5$ Hz			
SSB phase noise assuming 10MHz carrier	ULN (dBc/Hz)	LN (dBc/Hz)	Standard (dBc/Hz)	
	1 Hz	$< -110$	$< -105$	$< -100$
	10 Hz	$< -140$	$< -135$	$< -130$
	100 Hz	$< -150$	$< -145$	$< -140$
	1000 Hz	$< -160$	$< -155$	$< -150$
10000 Hz	$< -168$	$< -165$	$< -160$	
Output signal level	7 dBm $\pm$ 1 Up to 10 dBm on request			
Output impedance	50 $\Omega$ $\pm$ 10%			
Harmonics	-40 dBc			
Spurious signals	-120 dBc			
Power consumption during warm-up	Standard	Fast		
	4W	6W		
Nominal power consumption	1.5 W			
Maximum power consumption in operation	2.5 W			
Volume	$< 75$ cm <sup>3</sup>			
Power supply	12 V	15V		
Warm-up time (accuracy $< \pm 2 \times 10^{-8}$ at 25°C)	Standard	Fast		
	10 minutes	5 minutes		
Mass	100 gr			

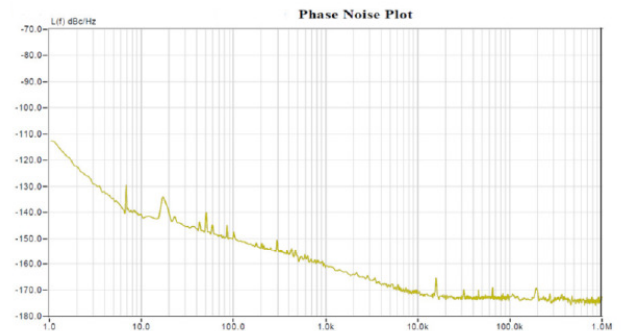
**FUNCTIONAL BLOCK DIAGRAM OF THE LNMO**



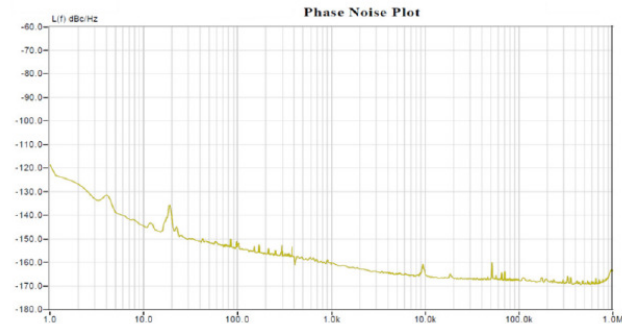
- 1- Optional telemetry output
- 2- RF GND output
- 3- RF output
- 4- Control voltage input
- 5- Voltage reference output
- 6- Supply GND input
- 7- Supply Voltage input

**Typical LNMO Phase Noise**

LNMO Phase noise at 10MHz



LNMO Phase noise at 5 MHz



Type A2x-S001 at 10MHz			
Parameter	Value		
Connection: Power, RF Output, Control voltage, Ref Voltage, TM	7 solderable pins or 5 solderable pins +SMA		
Mechanical interface	flat base plate		
Mechanical fixation	4 x M2 screw		
Max. base plate operating temperature	70 °C	60°C	50°C
Min. base plate operating temperature	-30°C	-20°C	0°C
Storage temperature	-40 to 85 °C		
First natural resonance	$> 800$ Hz		
Random Vibration tested, with axis perpendicular to the mounting plane.	20 - 100 Hz	$+9$ dB/oct	
	100- 500 Hz	1 (1.5) g <sup>2</sup> /Hz**	
	500- 2000 Hz	$-6$ dB/oct	
Duration	60 (180) sec/axis**		
Random Vibration tested, with axis parallel to the mounting plane.	20 - 1000 Hz	0.14(0.22) g <sup>2</sup> /Hz**	
	1000 - 2000 Hz	$-6$ dB/oct	
	Duration	60 (120) sec/axis**	
Sinusoidal vibration	5 - 20 Hz	11 mm 0-peak	
	20 - 100 Hz	25 g	
Sweep rate	2(1) oct/min.**		
Life time / MTBF	15 years/9 Mio hrs		
Pressure sensitivity vacuum to atmosphere (thermal effect)	$< \pm 5 \times 10^{-8}$ @25°C		

\* Other frequencies (5 MHz to 40 MHz) and related specifications available upon request.

\*\* Values in brackets only applicable for qualification testing